Small Signal MOSFET

60 V, 115 mA, N-Channel SOT-23

Features

• Pb-Free Packages are Available



Rating	Symbol	Value	Unit
Drain-Source Voltage	V _{DSS}	60	Vdc
Drain–Gate Voltage (R_{GS} = 1.0 MΩ)	V_{DGR}	60	Vdc
Drain Current - Continuous $T_C = 25^{\circ}C$ (Note 1) $T_C = 100^{\circ}C$ (Note 1) - Pulsed (Note 2)	I _D I _D I _{DM}	±115 ±75 ±800	mAdc
Gate-Source Voltage - Continuous - Non-repetitive (t _p ≤ 50 μs)	V _{GS} V _{GSM}	±20 ±40	Vdc Vpk

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board (Note 3) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate,(Note 4) T _A = 25°C	P _D	300	mW mW/°C
Derate above 25°C	G a-	2.4	,
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	-55 to +150	°C

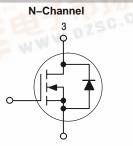
- The Power Dissipation of the package may result in a lower continuous drain current.
- 2. Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.
- 3. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.
- 4. Alumina = $0.4 \times 0.3 \times 0.025$ in 99.5% alumina.



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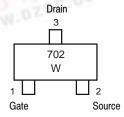
V _{(BR)DSS}	R _{DS(on)} MAX	I _D MAX
60 V	7.5 Ω @ 10 V, 500 mA	115 mA



MARKING DIAGRAM & PIN ASSIGNMENT



SOT-23 CASE 318 STYLE 21



702 = Device Code W = Work Week

ORDERING INFORMATION

		Company State State of Company and Company
Device	Package	Shipping [†]
2N7002LT1	SOT-23	3000 Tape & Reel
2N7002LT3	00. 20	10,000 Tape & Reel
2N7002LT1G	SOT-23	3000 Tape & Reel
2N7002LT3G	(Pb-free)	10,000 Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

CI	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						I
Drain-Source Breakdown Volta (V _{GS} = 0, I _D = 10 μAdc)	V _{(BR)DSS}	60	_	-	Vdc	
Zero Gate Voltage Drain Curre (V _{GS} = 0, V _{DS} = 60 Vdc)	I _{DSS}	-	_ _	1.0 500	μAdc	
Gate-Body Leakage Current, F (V _{GS} = 20 Vdc)	e–Body Leakage Current, Forward V _{GS} = 20 Vdc)		-	_	100	nAdc
Gate-Body Leakage Current, F (V _{GS} = -20 Vdc)	ate-Body Leakage Current, Reverse (V _{GS} = -20 Vdc)			_	-100	nAdc
ON CHARACTERISTICS (Note	e 5)					
Gate Threshold Voltage (V _{DS} = V _{GS} , I _D = 250 μAdc)		V _{GS(th)}	1.0	_	2.5	Vdc
On–State Drain Current $(V_{DS} \ge 2.0 V_{DS(on)}, V_{GS} = 1)$	0 Vdc)	I _{D(on)}	500	_	-	mA
Static Drain-Source On-State $(V_{GS} = 10 \text{ Vdc}, I_D = 500 \text{ m/s})$ $(V_{GS} = 5.0 \text{ Vdc}, I_D = 50 \text{ mA})$	Adc)	V _{DS(on)}	- -	- -	3.75 0.375	Vdc
Static Drain–Source On–State $(V_{GS} = 10 \text{ V}, I_D = 500 \text{ mAdd})$ $(V_{GS} = 5.0 \text{ Vdc}, I_D = 50 \text{ mAdd})$	r _{DS(on)}	- - -	- - -	7.5 13.5 7.5	Ohms	
	T _C = 125°C		_	-	13.5	
Forward Transconductance $(V_{DS} \ge 2.0 \ V_{DS(on)}, \ I_D = 200 \ m_{\odot}$	Adc)	9FS	80	_	-	mmhos
DYNAMIC CHARACTERISTIC	s					
Input Capacitance (V _{DS} = 25 Vdc, V _{GS} = 0, f =	: 1.0 MHz)	C _{iss}	-	-	50	pF
Output Capacitance (V _{DS} = 25 Vdc, V _{GS} = 0, f =	C _{oss}	-	_	25	pF	
Reverse Transfer Capacitance (V _{DS} = 25 Vdc, V _{GS} = 0, f =	C _{rss}	-	-	5.0	pF	
SWITCHING CHARACTERIST	TICS (Note 5)				•	
Turn-On Delay Time	$(V_{DD} = 25 \text{ Vdc}, I_D \cong 500 \text{ mAdc},$	t _{d(on)}	-	-	20	ns
Turn-Off Delay Time	_ '			_	40	ns
BODY-DRAIN DIODE RATING						
Diode Forward On-Voltage (I _S = 11.5 mAdc, V _{GS} = 0 V	V _{SD}	-	_	-1.5	Vdc	
Source Current Continuous (Body Diode)	I _S	-	_	-115	mAdc	
Source Current Pulsed	I _{SM}	_	_	-800	mAdc	

^{5.} Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%.

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TYPICAL ELECTRICAL CHARACTERISTICS

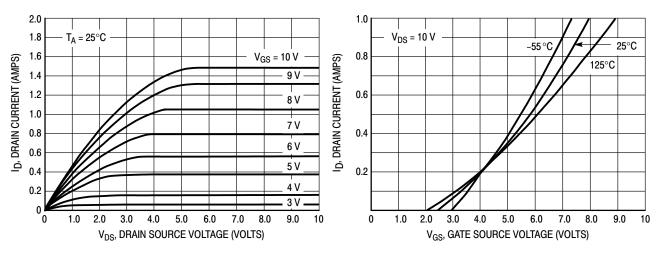


Figure 1. Ohmic Region

Figure 2. Transfer Characteristics

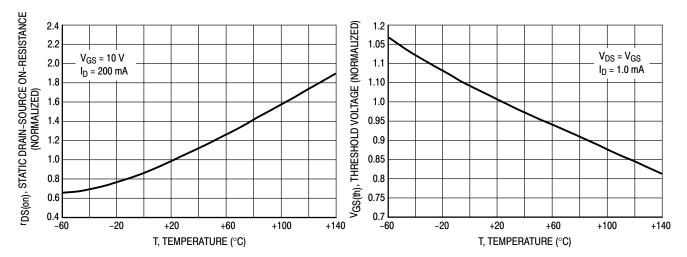


Figure 3. Temperature versus Static Drain-Source On-Resistance

Figure 4. Temperature versus Gate Threshold Voltage

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AH**

NOTES:

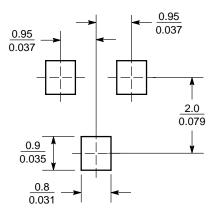
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS
 IS THE MINIMUM THICKNESS OF BASE
- 318-03 AND -07 OBSOLETE, NEW STANDARD 318-08

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.1102	0.1197	2.80	3.04
В	0.0472	0.0551	1.20	1.40
С	0.0350	0.0440	0.89	1.11
D	0.0150	0.0200	0.37	0.50
G	0.0701	0.0807	1.78	2.04
Н	0.0005	0.0040	0.013	0.100
J	0.0034	0.0070	0.085	0.177
K	0.0140	0.0285	0.35	0.69
L	0.0350	0.0401	0.89	1.02
S	0.0830	0.1039	2.10	2.64
٧	0.0177	0.0236	0.45	0.60

STYLE 21:

- PIN 1. GATE
 - 2. SOURCE DRAIN

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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